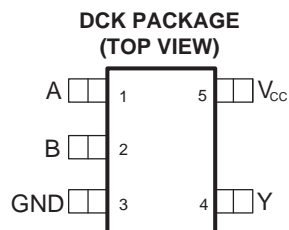


Low-Power Single 2-Input Positive-AND Gate

Check for Samples: [SN74AUP1G08-Q1](#)

FEATURES

- **AEC-Q100 Qualified with the Following Results:**
 - Device Temperature Grade 1: –40°C to 125°C Ambient Operating Temperature Range
 - Device HBM ESD Classification Level H2
 - Device CDM ESD Classification Level C3B
- Available in the Texas Instruments NanoStar™ Package
- **Low Static-Power Consumption:**
 $I_{CC} = 0.9 \mu\text{A Max}$
- **Low Dynamic-Power Consumption:**
 $C_{pd} = 4.3 \text{ pF Typ at } 3.3 \text{ V}$
- **Low Input Capacitance:** $C_i = 1.5 \text{ pF Typ}$
- **Low Noise: Overshoot and Undershoot**
 $< 10\% \text{ of } V_{CC}$
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Schmitt-Trigger Action Allows Slow Input Transition and Better Switching Noise Immunity at the Input ($V_{hys} = 250 \text{ mV, Typ at } 3.3 \text{ V}$)**
- **Wide Operating V_{CC} Range of 0.8 V to 3.6 V**
- **Optimized for 3.3-V Operation**
- **3.6-V Input/Output (I/O) Tolerant to Support Mixed-Mode Signal Operation**
- **$t_{pd} = 4.3 \text{ ns Max at } 3.3 \text{ V}$**
- **Suitable for Point-to-Point Applications**
- **Latch-Up Performance Exceeds 100 mA Per JESD-78, Class II**



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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DESCRIPTION

The AUP family is TI's premier solution to the low-power needs of the industry in battery-powered portable applications. This family ensures a very low static- and dynamic-power consumption across the entire V_{CC} range of 0.8 V to 3.6 V, resulting in increased battery life (see Figure 1). This product also maintains excellent signal integrity (see the very low undershoot and overshoot characteristics shown in Figure 2).

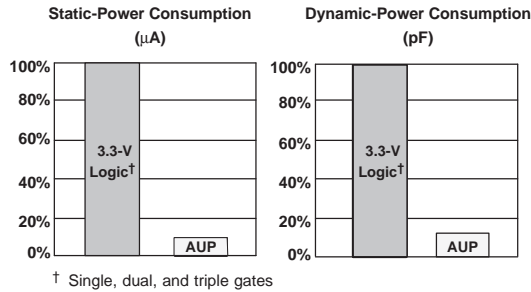


Figure 1. AUP – The Lowest-Power Family

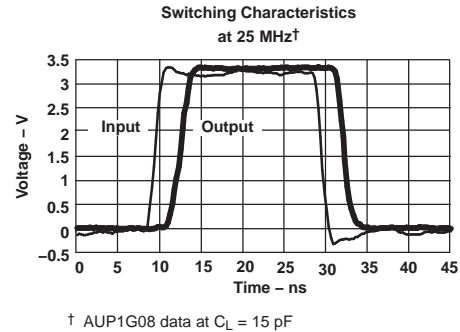


Figure 2. Excellent Signal Integrity

This single 2-input positive-AND gate performs the Boolean function: $Y = A \bullet B$ or $Y = \overline{\overline{A} + \overline{B}}$ in positive logic.

NanoStar package technology is a major breakthrough in integrated circuit (IC) packaging concepts, because it uses the die as the package.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION⁽¹⁾

T_A	ORDERABLE PART NUMBER ⁽²⁾	TOP-SIDE MARKING
-40°C to 125°C	SN74AUP1G08QDCKRQ1	SIT

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

FUNCTION TABLE

INPUTS		OUTPUT Y
A	B	
L	L	L
L	H	L
H	L	L
H	H	H

LOGIC DIAGRAM (POSITIVE LOGIC)

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
V _{CC}	Supply voltage range	-0.5	4.6	V	
V _I	Input voltage range ⁽²⁾	-0.5	4.6	V	
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	4.6	V	
V _O	Output voltage range in the high or low state ⁽²⁾	-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±20	mA
	Continuous current through V _{CC} or GND			±50	mA
T _{stg}	Storage temperature range	-65	150	°C	
ESD ratings	Human body model (HBM) AEC-Q100 classification level H2			2	kV
	Charged device model (CDM) AEC-Q100 classification level C3B			750	V

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		SN74AUP1G08-Q1	UNIT
		DCK (5 PINS)	
θ _{JA}	Junction-to-ambient thermal resistance	304.7	°C/W
θ _{JCtop}	Junction-to-case (top) thermal resistance	115.3	
θ _{JB}	Junction-to-board thermal resistance	80.3	
ψ _{JT}	Junction-to-top characterization parameter	3.5	
ψ _{JB}	Junction-to-board characterization parameter	79.4	
θ _{JCbot}	Junction-to-case (bottom) thermal resistance	N/A	

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	0.8	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 0.8 V	V _{CC}	V
		V _{CC} = 1.1 V to 1.95 V	0.65 × V _{CC}	
		V _{CC} = 2.3 V to 2.7 V	1.6	
		V _{CC} = 3 V to 3.6 V	2	
V _{IL}	Low-level input voltage	V _{CC} = 0.8 V	0	V
		V _{CC} = 1.1 V to 1.95 V	0.35 × V _{CC}	
		V _{CC} = 2.3 V to 2.7 V	0.7	
		V _{CC} = 3 V to 3.6 V	0.9	
V _I	Input voltage	0	3.6	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 0.8 V	-20	μA
		V _{CC} = 1.1 V	-1.1	
		V _{CC} = 1.4 V	-1.7	
		V _{CC} = 1.65 V	-1.9	
		V _{CC} = 2.3 V	-3.1	
		V _{CC} = 3 V	-4	
I _{OL}	Low-level output current	V _{CC} = 0.8 V	20	μA
		V _{CC} = 1.1 V	1.1	
		V _{CC} = 1.4 V	1.7	
		V _{CC} = 1.65 V	1.9	
		V _{CC} = 2.3 V	3.1	
		V _{CC} = 3 V	4	
Δt/Δv	Input transition rise or fall rate	V _{CC} = 0.8 V to 3.6 V	200	ns/V
T _A	Operating free-air temperature	-40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = -40°C to 85°C		T _A = 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -20 μA	0.8 V to 3.6 V	V _{CC} - 0.1			V _{CC} - 0.1		V _{CC} - 0.1		V
	I _{OH} = -1.1 mA	1.1 V	0.75 × V _{CC}			0.7 × V _{CC}		0.7 × V _{CC}		
	I _{OH} = -1.7 mA	1.4 V	1.11			1.03		1.03		
	I _{OH} = -1.9 mA	1.65 V	1.32			1.3		1.3		
	I _{OH} = -2.3 mA	2.3 V	2.05			1.97		1.97		
	I _{OH} = -3.1 mA		1.9			1.85		1.85		
	I _{OH} = -2.7 mA	3 V	2.72			2.67		2.67		
	I _{OH} = -4 mA		2.6			2.55		2.55		

ELECTRICAL CHARACTERISTICS (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = -40°C to 85°C		T _A = 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OL}	I _{OL} = 20 μA	0.8 V to 3.6 V			0.1		0.1		0.1	V
	I _{OL} = 1.1 mA	1.1 V			0.3 × V _{CC}		0.3 × V _{CC}		0.3 × V _{CC}	
	I _{OL} = 1.7 mA	1.4 V			0.31		0.37		0.37	
	I _{OL} = 1.9 mA	1.65 V			0.31		0.35		0.35	
	I _{OL} = 2.3 mA	2.3 V			0.31		0.33		0.33	
	I _{OL} = 3.1 mA				0.44		0.45		0.45	
	I _{OL} = 2.7 mA	3 V			0.31		0.33		0.33	
	I _{OL} = 4 mA				0.44		0.45		0.45	
I _I	A or B input	V _I = GND to 3.6 V			0.1		0.5		0.5	μA
I _{off}		V _I or V _O = 0 V to 3.6 V			0.2		0.6		0.8	μA
ΔI _{off}		V _I or V _O = 0 V to 3.6 V			0.2		0.6		0.8	μA
I _{CC}		V _I = GND or (V _{CC} to 3.6 V), I _O = 0			0.5		0.9		1.2	μA
ΔI _{CC}		V _I = V _{CC} - 0.6 V ⁽¹⁾ , I _O = 0			40		50		23	μA
C _i	V _I = V _{CC} or GND	0 V		1.5						pF
		3.6 V		1.5						
C _o	V _O = GND	0 V		3						pF

 (1) One input at V_{CC} - 0.6 V, other input at V_{CC} or GND.

SWITCHING CHARACTERISTICS

 over recommended operating free-air temperature range, C_L = 5 pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = -40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	A or B	Y	0.8 V		18				ns
			1.2 V ± 0.1 V	2.6	7.3	12.8	2.1	15.6	
			1.5 V ± 0.1 V	1.4	5.2	8.7	0.9	10.3	
			1.8 V ± 0.15 V	1	4.2	6.6	0.5	8.2	
			2.5 V ± 0.2 V	1	3	4.4	0.5	5.5	
			3.3 V ± 0.3 V	1	2.4	3.5	0.5	4.3	

SWITCHING CHARACTERISTICS

 over recommended operating free-air temperature range, C_L = 10 pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = -40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	A or B	Y	0.8 V		21				ns
			1.2 V ± 0.1 V	1.5	8.5	14.7	1	17.2	
			1.5 V ± 0.1 V	1	6.2	10	0.5	11.3	
			1.8 V ± 0.15 V	1	5	7.7	0.5	9	
			2.5 V ± 0.2 V	1	3.6	5.2	0.5	6.1	
			3.3 V ± 0.3 V	1	2.9	4.2	0.5	4.7	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $C_L = 15$ pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Y	0.8 V	24					ns
			$1.2\text{ V} \pm 0.1\text{ V}$	3.6	9.9	16.3	3.1	19.9	
			$1.5\text{ V} \pm 0.1\text{ V}$	2.3	7.2	11.1	1.8	13.2	
			$1.8\text{ V} \pm 0.15\text{ V}$	1.6	5.8	8.7	1.1	10.6	
			$2.5\text{ V} \pm 0.2\text{ V}$	1	4.3	5.9	0.5	7.3	
			$3.3\text{ V} \pm 0.3\text{ V}$	1	3.4	4.8	0.5	5.9	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $C_L = 30$ pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

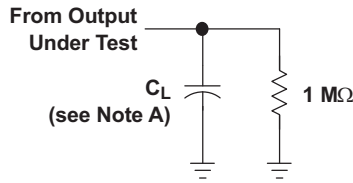
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		$T_A = 125^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	0.8 V	32.8							ns
			$1.2\text{ V} \pm 0.1\text{ V}$	4.9	13.1	20.9	4.4	25.5	4.4	27.8	
			$1.5\text{ V} \pm 0.1\text{ V}$	3.4	9.5	14.2	2.9	16.9	2.9	18	
			$1.8\text{ V} \pm 0.15\text{ V}$	2.5	7.7	11	2	13.5	2	19.7	
			$2.5\text{ V} \pm 0.2\text{ V}$	1.8	5.7	7.6	1.3	9.4	1.3	11	
			$3.3\text{ V} \pm 0.3\text{ V}$	1.5	4.7	6.2	1	7.5	1	8.7	

OPERATING CHARACTERISTICS

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$f = 10\text{ MHz}$	0.8 V	4	pF
			$1.2\text{ V} \pm 0.1\text{ V}$	4	
			$1.5\text{ V} \pm 0.1\text{ V}$	4	
			$1.8\text{ V} \pm 0.15\text{ V}$	4	
			$2.5\text{ V} \pm 0.2\text{ V}$	4.1	
			$3.3\text{ V} \pm 0.3\text{ V}$	4.3	

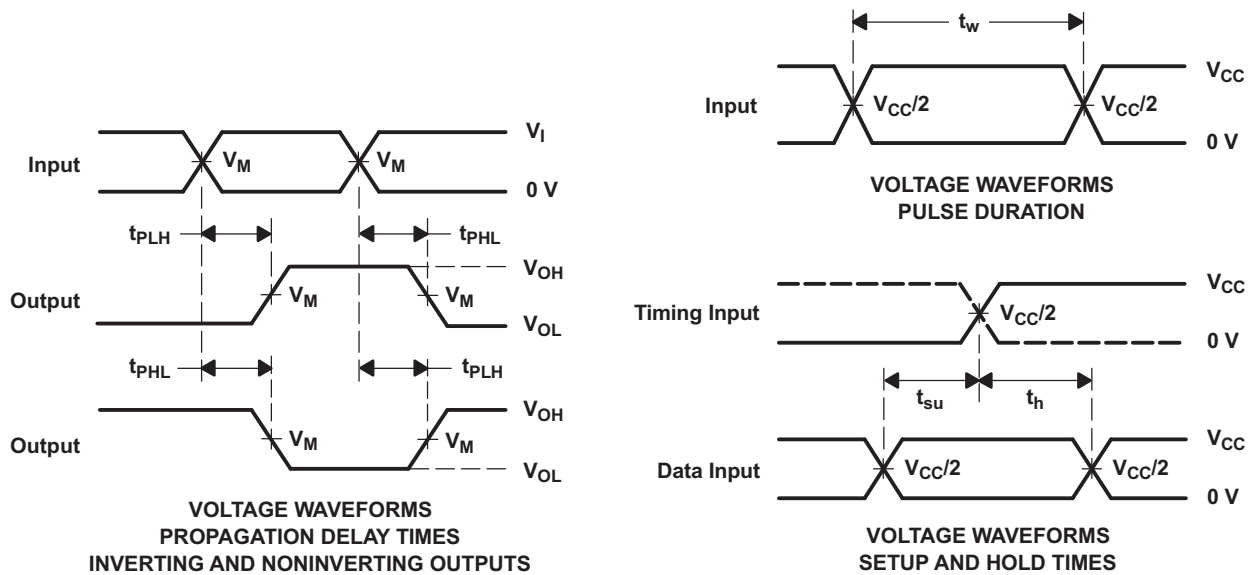
PARAMETER MEASUREMENT INFORMATION
(Propagation Delays, Setup and Hold Times, and Pulse Duration)



LOAD CIRCUIT

$T_A = -25^\circ\text{C to } 85^\circ\text{C}$

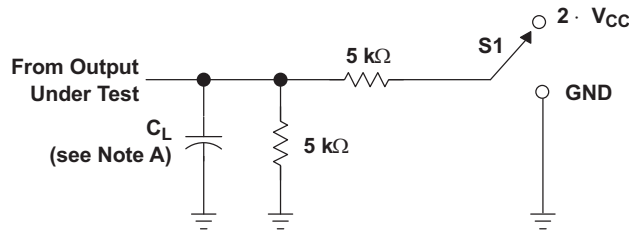
	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



- NOTES: A. C_L includes probe and jig capacitance.
 B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, slew rate $\geq 1 \text{ V/ns}$.
 C. The outputs are measured one at a time, with one transition per measurement.
 D. t_{PLH} and t_{PHL} are the same as t_{pd} .
 E. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

**PARAMETER MEASUREMENT INFORMATION
(Enable and Disable Times)**

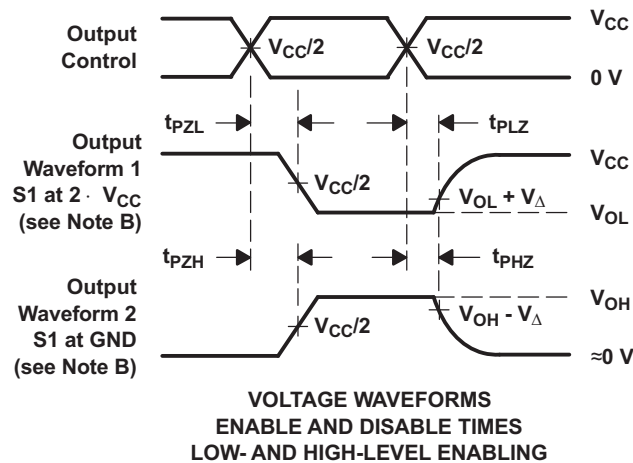


TEST	S1
t_{PLZ}/t_{PZL}	$2 \cdot V_{CC}$
t_{PHZ}/t_{PHL}	GND

LOAD CIRCUIT

$T_A = -25^\circ\text{C to } 85^\circ\text{C}$

	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_Δ	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING**

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, slew rate $\geq 1 \text{ V/ns}$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AUP1G08QDCKRQ1	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	(SIJ, SIT)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74AUP1G08-Q1 :

- Catalog : [SN74AUP1G08](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1G08QDCKRQ1	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP1G08QDCKRQ1	SC70	DCK	5	3000	190.0	190.0	30.0

DCK0005A



PACKAGE OUTLINE

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



4214834/C 03/2023

NOTES:

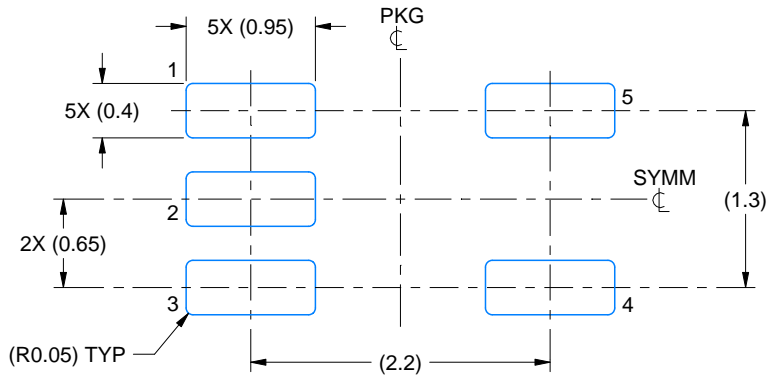
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.

EXAMPLE BOARD LAYOUT

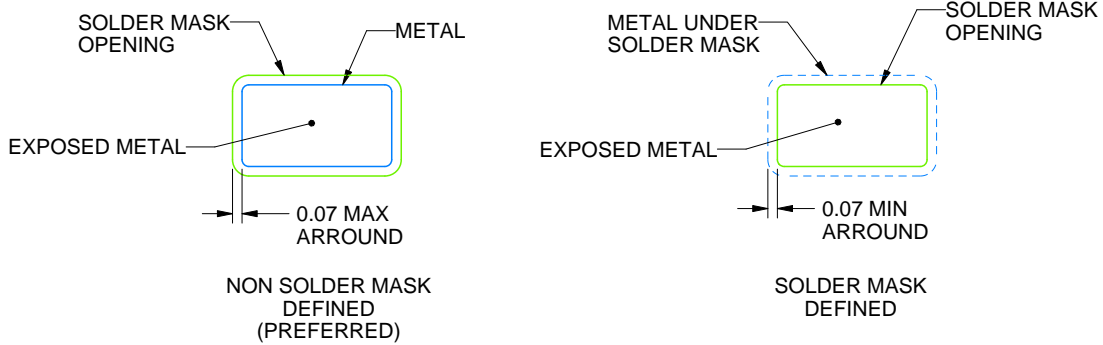
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

4214834/C 03/2023

NOTES: (continued)

- 4. Publication IPC-7351 may have alternate designs.
- 5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

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